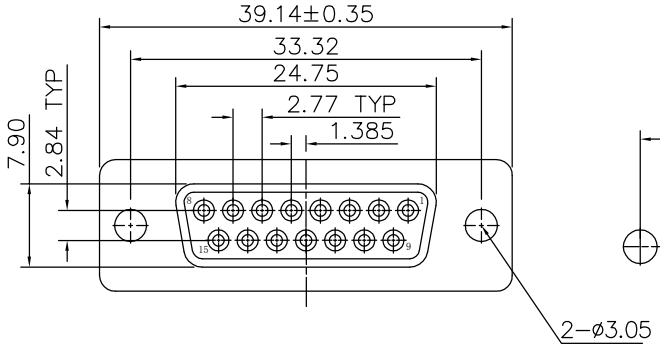
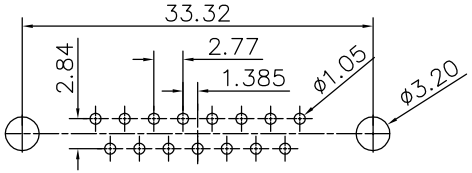
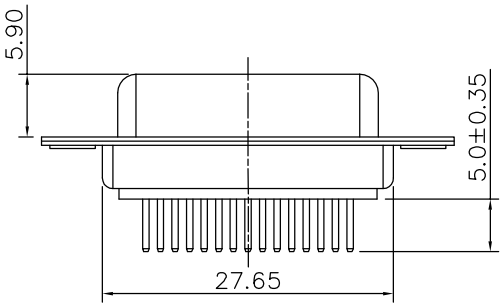
The product using material and processing must conform to the "WL-PZ-001"HSF technical standard control requirements

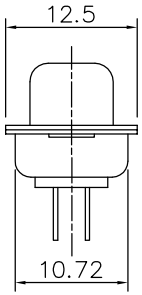
RoHS





PCB layout





NOTE

1.MATERIAL:

1 1.1 INSULATOR: PBT+30% GLASS FIBER UL94V-0
COLOR:BLACK

1.2 TERMINAL: COPPER ALLOY BRASS T=0.20±0.02mm
GOLD FLASH ON CONTACT AREA AND TIN 80U" ON SOLDER TAIL; NICKEL:30U" ON THE BASE

1.3 SHELL: FRONT SHELL:SPCC-SD T=0.35±0.02mm
PLATING:Cu50u"/Ni50u" ;
REAR SHELL:SPCC-SD T=0.35±0.02mm
PLATING:Cu50u"/Tin80u"

1.4 BOARD LOCK: COPPER ALLOY, PLATING: Cu50u"/Ni40u"

1.5 SCREW: STEEL, PLATING: Cu50u"/Ni40u"

1.6 SALT SPRAY: PLATING GOLD, 24H; OTHER PART: 12H .

2.ELECTRICAL:

2.1 INSULATOR RESISTANCE: 1000MEGOHMS MIN AT 500V DC.

2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC R.M.S

2.3 VOLTAGE TATING: 40V AC (RMS) CONTINUOUS MAX.

2.4 CURRENT RATING: 3A.

2.5 CONTGACT RESISTANCE: 30 MILLIOHMS MAX.

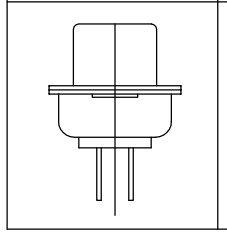
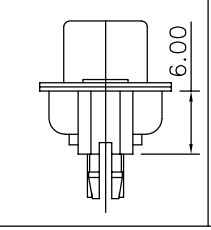
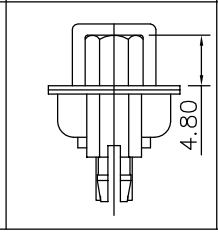
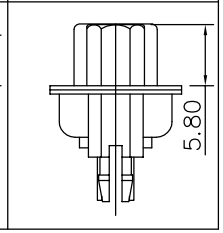
3.MECHANICAL

3.1 INSERTION/EXTRACTION FORCE PER CONTACT: 5.0Kgf Max
0.45Kgf Min.

4.ENVIRONMENTAL

TEMPERATURE RANGE:-55°C TO + 105°C.

Specification Type

A	B	C	D
			

ORDER INFORMTION

P/N:WLDBF0-151XXX028

Number of Contact

Contact Type
1: DIP

Plating Contact
1: Gold Flash
3: Au: 3U"
6: Au: 30U"

SCREW
A: Specification Type A
B: Specification Type B
C: Specification Type C
D: Specification Type D

Housing color
A: Black
S: Nature

REV.	REVISION RECORD	DATE
A0	NEW RELEASE	21.01.13
A1	ADD MATERIAL THICK AND PLATING 1	23.04.27

GENERAL TOLERANCES	
LINEAR	ANGLES
0.0±0.35	X°REF±6°
0.00±0.25	X°±3°
0.000±0.10	X°X' ±2°

UNIT: mm

SIZE: A4

SCALE: 1:1	NAME	DATE
APPROVED	Wang_jr	21.01.13
DESIGNER	Ou_jian	21.01.13
DRAWN	Hou-lanxuan	21.01.13

PART.NO: WLDBF0-151XXX028

DWG.NO: ENDE05

TITLE: DP 15F DIP

万连科技
WanLian Technology Co., Ltd

REV: A0

SHEET: 1/1